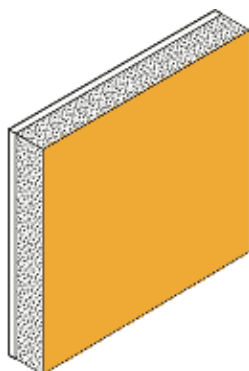


## Knauf Thermal Laminate Plus



CFC-free extruded polystyrene bonded to 9.5mm Knauf Wallboard. Low thermal conductivity means that thinner laminates can be used compared with expanded polystyrene laminates.

Knauf Thermal Laminate Plus has a Thermal Conductivity figure for wallboard of  $k = 0.16\text{W/mK}$  and for Extruded Polystyrene of  $0.030\text{W/mK}$ .

Thermal Resistance:

27mm =  $0.71\text{m}^2\text{ K/W}$

35mm =  $1.00\text{m}^2\text{ K/W}$

40mm =  $1.19\text{m}^2\text{ K/W}$

45mm =  $1.37\text{m}^2\text{ K/W}$

55mm =  $1.75\text{m}^2\text{ K/W}$

Dimensions (mm)			Article No	Pack Details		
Thickness	Width	Length		Boards	$\text{m}^2$	Tonnes (Approx.)
27	1200	2400	471 28 224	36	103.7	0.71
35	1200	2400	471 24 424	28	80.6	0.58
40	1200	2400	471 20 524	25	72	0.53
45	1200	2400	471 24 724	22	63.4	0.47
55	1200	2400	470 20 724	16	46.1	0.36